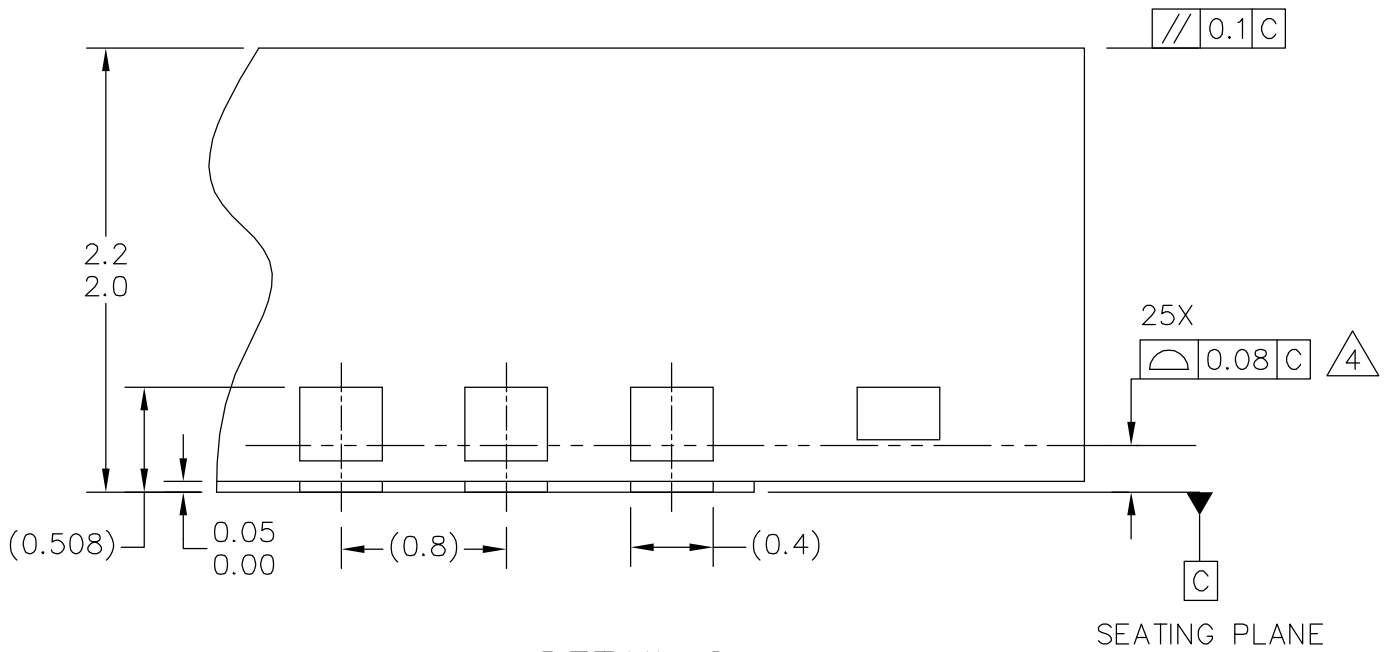


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TITLE: PQFN (SAW), THERMALLY ENHANCED 8 X 8 X 2.1, 0.8 PITCH, 24 TERMINAL	DOCUMENT NO: 98ASA10760D      REV: B	
	STANDARD: NON-JEDEC	
	SOT1664-1	11 MAR 2016




DETAIL G  
VIEW ROTATED 90° CW

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		STANDARD: NON-JEDEC	
		SOT1664-1	11 MAR 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.

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